ON Semiconductor				10/15/2019
Base Part		HCPL2531		Pb-free
Orderable Part		HCPL2531SD	Total weight (mg)	542.964
Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight
Coupling Gel	64	3-Methacryloxypropyltrimethoxysilane (C10H20O5Si)	2530-85-0	100
Die	0.099	Gallium Arsenide (AsGa)	1303-00-0	33.33333333
		Silicon (Si)	7440-21-3	66.66666667
Die Attach	0.25	Silver (Ag)	7440-22-4	83
		Ortho Cresol Novolac Resin	29690-82-2	17
Lead Frame	115	Zinc (Zn)	7440-66-6	0.12
		Iron (Fe)	7439-89-6	2.35869565
		Copper (Cu)	7440-50-8	97.5
		Phosphorus (P)	7723-14-0	0.02130435
Mold Compound-Black	93.303	Brominated Epoxy Resin-2	68541-56-0	2.49991962
		Ortho Cresol Novolac Resin	29690-82-2	14.9995177
		Antimony Trioxide (Sb2O3)	1309-64-4	1.99993569
		Carbon Black (C)	1333-86-4	0.50319925
		Fused Silica (SiO2)	60676-86-0	69.99774927
		Phenolic Resin (Novolac)	9003-35-4	9.99967847
Mold Compound-White	258.662	Titanium Dioxide (TiO2)	13463-67-7	20.25809744
		Zirconium Dioxide (ZrO2)	1314-23-4	0.50258639
		Ortho Cresol Novolac Resin	29690-82-2	76.0304954
		Silica Amorphous (SiO2)	7631-86-9	2.16498751
		Aluminum Trioxide (Al2O3)	1344-28-1	1.04383327
Plating	11.6	Tin (Sn)	7440-31-5	100
Wire Bond - Au	0.05	Gold (Au)	7440-57-5	100

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels fo dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:

http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF